Abstract

A semiconductor chip pickup apparatus comprises support means for supporting a tape having many semiconductor chips adhered onto the face of the tape; and pickup means for individually picking up the semiconductor chips from the face of the tape supported on the support means. The support means includes a plurality of support lines, extending parallel at spaced locations, for supporting the back of the tape. Suction means is disposed for sucking the back of the tape, thereby peeling the tape from the semiconductor chips in regions other than the support lines.



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